



Board Level Shielding
Design & Fabrication

Item No:	Description:	Material:
MS263-20	DRAWN RF SHEILD FRAME + COVER	TIN STEEL (See Note 1-2)
Note: (1) TS275E 8.4/8.4 (2) Electrolytic Tin Plate As Per EN 10202:2001 Min Tin Thickness 3.5 μ m (3) General tolerance ± 0.2 mm Non Dimensioned items remain Masach Technologies LTD property.		
www.masach.com		MMGS / Print 1:1 / A4